electron beams, and removing the cured composition from the shaped part or films.

REMARKS

In response to the Office Action, the present application has been reviewed and amended. It is respectfully requested that the application be reconsidered in light of the above amendments and following remarks.

In the Office Action, the Examiner objected to Applicants' cross-reference to the prior applications. By way of the above amendment, the cross-reference has been corrected and the Examiner's objection is now believed to be overcome.

With respect to the claims, the Examiner rejected claims 1 and 2 under 35 U.S.C. § 103 as being unpatentable over Coady et al in view of Newell. The claims also were rejected under 35 U.S.C. § 102(b) as being anticipated by, or in the alternative, under 35 U.S.C. § 103(a) as obvious, over Hodakowski. For the following reasons, the Examiner's rejections are traversed.

Originally pending claims 1 and 2 have been amended in order to more particularly describe the present invention and new claims 3 – 16 have been added. All claims recite a resin composition for use in a process for producing a cured film having the memory of a specified shape. The claims then recite the composition of the material. None of the references cited by the Examiner disclose or suggest such a resin composition for use in a process for producing a cured film having the memory of a specified shape.

The references cited by the Examiner only become marginally relevant when the claims are used as a roadmap to read disclosure and insight into the references which is not there. This

is impermissible hindsight. None of the cited references disclose or suggest a resin composition for use in a process for producing a cured film as described by the claims. For these reasons, it is respectfully submitted that the prior art relied on by the Examiner does not render any of the present claims unpatentable.

It is respectfully submitted that all claims in this application are in condition for allowance and an early indication of such allowance is earnestly requested.

Respectfully submitted,

By: _____

Thomas L. Peterson
Registration No. 30,969

Banner & Witcoff, LTD.
Eleventh Floor
1001 G Street, N.W.
Washington, D.C. 20001-4597
(202) 508-9100

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MARKED-UP COPY OF AMENDMENT

IN THE SPECIFICATION

Please amend page 1, line 3 of the specification as follows:

This application is a continuation of application Serial No. 08/544,408, filed October 10, 1995, which is a continuation of application Serial No. 07/747,610, ~~07/484,610~~ filed August 20, 1991, the entire contents of which are incorporated herein by reference.

IN THE CLAIMS

Please amend the claims as follows:

1. (Amended) A resin composition for use in a process for producing a cured film having the memory of a specified shape, ~~which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films,~~ said resin composition comprising:

~~(a)~~ an oligomer compound having ~~that has~~ at least one acryloyl ~~or methacryloyl~~ group in the molecule and ~~that~~ has a glass transition temperature~~, Tg,~~ of lower than 50°C after polymerization; ~~and~~

~~(b)~~ a low-molecular weight compound that has in its molecule one reactive double bond capable of polymerization with ~~the~~ said oligomer compound ~~(a)~~ and that has a glass transition temperature~~, Tg,~~ higher than at least 90°C after polymerization.~~; or~~

~~(b') a mixture of two or more low-molecular-weight compounds that have in their molecule one reactive double bond capable of copolymerization with the oligomer compound (a) and that have a glass transition temperature, Tg, higher than 90° C after polymerization.~~

2. (Amended) A resin compound for use in a process for producing a cured film having the memory of a specified shape, ~~which process comprises shaping a resin composition by either applying it onto a shaped part or placing it between films, curing said resin composition with electron beams, and removing the cured composition from the shaped part or films,~~ said resin composition comprising:

~~(a)~~ an oligomer compound that has at least one acryloyl ~~or methacryloyl~~ group in the molecule and that has a glass transition temperature~~, Tg,~~ lower than 50°C after polymerization; and

~~(b)~~ a ~~simple~~ urethane adduct of hydroxyethyl acrylate or hydoxyethyl methacrylate and a diisocyanate.~~; and~~

~~(c) an optional low-molecular-weight compound that has in its molecule at least one double bond capable of copolymerization with the oligomer compound (a).~~